

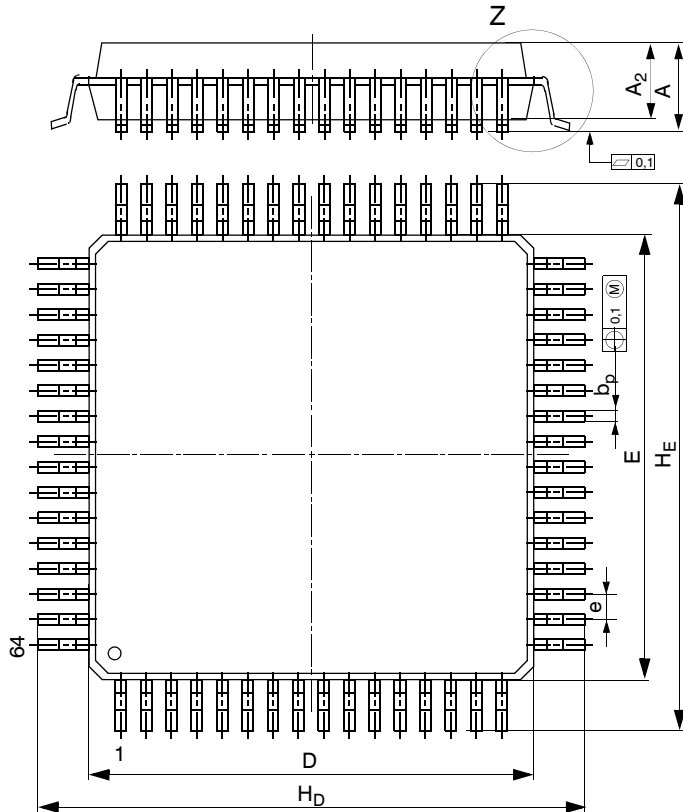

Package PQFP64
 (14x14)

MDS
742

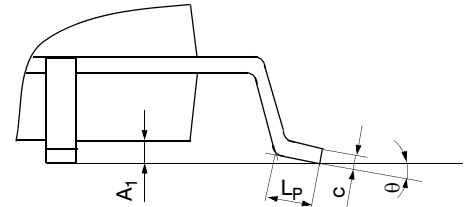
Dimensions in millimetres

 Supersedes
 Edition 11.96
 1. Amendment 11.97

Based on JEDEC JEP95: MO-108 BD-2 und MS-022 BE

1 Dimensions

Detail Z



Dimensions of Sub-Group B1	
e_{nom}	0,80
A_{max}	3,00
b_{Pmin}	0,30
b_{Pmax}	0,45
H_{Emin}	16,95
H_{Emax}	17,45
H_{Dmin}	16,95
H_{Dmax}	17,45
L_{Pmin}	0,73

- 2 Weight** $\leq 1,2$ g
- 3 Package Body Material** Low Stress Epoxy
- 4 Lead Material** FeNi-Alloy or Cu-Alloy
- 5 Lead Finish** solder plating
- 6 Lead Form** Z-bends

Dimensions of Sub-Group C1	
A_{1min}	0,10
A_{1max}	0,30
A_{2min}	2,55
A_{2max}	2,75
c_{min}	0,13
c_{max}	0,23
D_{min}	13,90
D_{max}	14,10
E_{min}	13,90
E_{max}	14,10
θ_{min}	0°
θ_{max}	7°

Zentrum Mikroelektronik Dresden AG		
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